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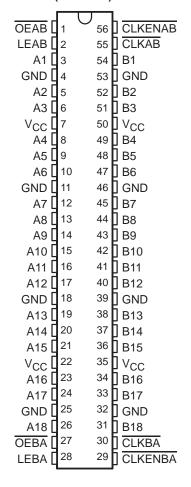
- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- UBT[™] (Universal Bus Transceiver)
 Combines D-Type Latches and D-Type
 Flip-Flops for Operation in Transparent,
 Latched, Clocked, or Clock-Enabled Mode
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 5 V, T_A = 25°C
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

These 18-bit universal bus transceivers combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, clocked, and clock-enabled modes.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable (CLKENAB and CLKENBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A-bus data is stored in the latch/flip-flop on the high-to-low transition of CLKAB. Output enable OEAB is active low. When OEAB is low, the outputs are active. When OEAB is high, the outputs are in the high-impedance state.

SN54ABT16600 . . . WD PACKAGE SN74ABT16600 . . . DGG OR DL PACKAGE (TOP VIEW)





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description (continued)

Data flow for B to A is similar to that of A to B, but uses OEBA, LEBA, CLKBA, and CLKENBA.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16600 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT16600 is characterized for operation from -40° C to 85° C.

FUNCTION TABLE†

	I	NPUTS			OUTPUT				
CLKENAB	OEAB	LEAB	CLKAB	Α	В				
Х	Н	Х	Х	Х	Z				
Х	L	Н	Χ	L	L				
Х	L	Н	Χ	Н	Н				
н	L	L	Χ	Χ	в ₀ ‡ в ₀ ‡				
н	L	L	Χ	Χ	в ₀ ‡				
L	L	L	\downarrow	L	L				
L	L	L	\downarrow	Н	Н				
L	L	L	Н	Χ	в ₀ ‡ в ₀ §				
L	L	L	L	Χ	В ₀ §				

[†] A-to-B <u>data flow</u> is <u>shown: B-to-A</u> flow is similar but uses OEBA, LEBA, <u>CLKBA</u>, and <u>CLKENBA</u>.

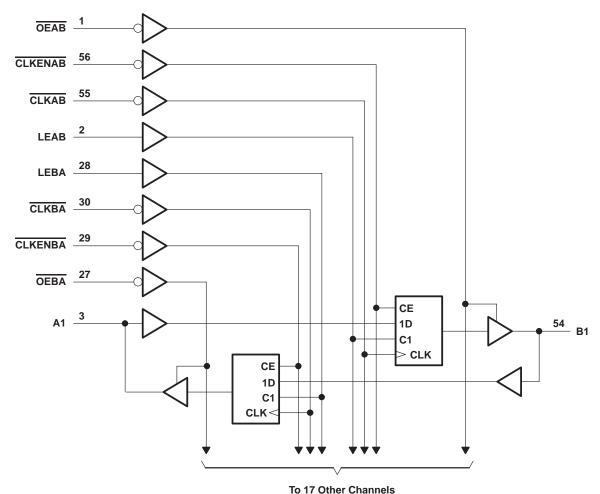


[‡] Output level before the indicated steady-state input conditions were established

[§] Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16600	96 mA
SN74ABT16600	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	81°C/W
DL package	
Storage temperature range, T _{stg}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

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recommended operating conditions (see Note 3)

				16600	SN74ABT16600		UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	EN	2		V
V _{IL}	V _{IL} Low-level input voltage			0.8		0.8	V
V _I Input voltage		0 0	VCC	0	VCC	V	
loh	IOH High-level output current		(,)	-24		-32	mA
lOL	Low-level output current		200	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	S. S	10		10	ns/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED		TEST CONDITIONS		Т	A = 25°C	;	SN54ABT16600		SN74ABT16600		UNIT		
l PA	PARAMETER VIK VOH VOL Vhys II Control inputs A or B ports	I IEST COI	NUITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT		
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2		-1.2		-1.2	V		
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5				
\/		V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V		
VOH		V 45V	I _{OH} = -24 mA	2			2				V		
		V _{CC} = 4.5 V	I _{OH} = -32 mA	2*					2				
V		V45V	I _{OL} = 48 mA			0.55		0.55			V		
VOL		V _{CC} = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V		
V _{hys}					100			2			mV		
1.	Control inputs	V 55V	V F V V				±1		<u>/</u> ±1		±1	μА	
<u> </u>	A or B ports	$V_{CC} = 5.5 \text{ V}, \qquad V_{I} = V_{CC} \text{ or GNI}$				±20		±20	±20		μΑ		
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	4	ζ.		±100	μΑ		
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50	Sporc	50		50	μΑ		
lo [‡]		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	2 -50	-180	-50	-180	mA		
IOZH§		V _{CC} = 5.5 V,	V _O = 2.7 V			10		10		10	μА		
		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-10		-10		-10	μА		
		V _{CC} = 5.5 V,	Outputs high			3		3		3			
VOH Vol. Vhys II Ioff ICEX IO [‡] IOZH IOZL AICC Ci	A or B ports	$I_{O} = 0$,	Outputs low			36		36		36	mA		
		$V_I = V_{CC}$ or GND	Outputs disabled			3		3		3			
ΔICC¶		$V_{CC} = 5.5 \text{ V}$, One in Other inputs at V_{CC}				50		50		50	μΑ		
Ci	Control inputs	V _I = 2.5 V or 0.5 V			3						pF		
C _{io}	A or B ports	V _O = 2.5 V or 0.5 \	/		9						pF		

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $[\]S$ The parameters $I_{\mbox{\scriptsize OZH}}$ and $I_{\mbox{\scriptsize OZL}}$ include the input leakage current.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

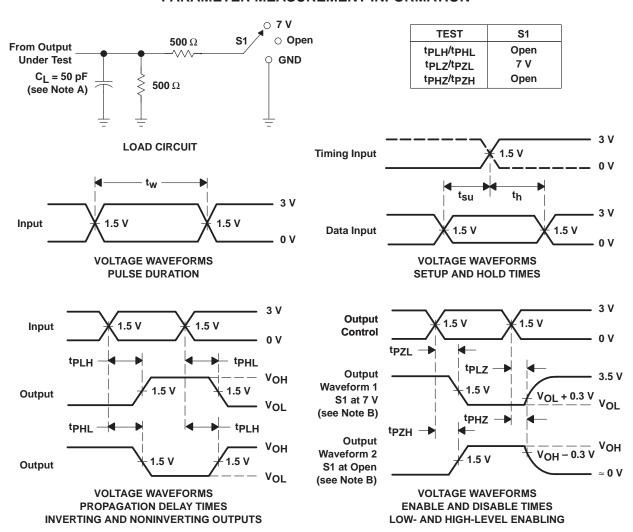
		SN54AB	Г16600	SN74AB1	UNIT		
			MIN	MAX	MIN	MAX	UNII
f _{clock}	Clock frequency		0	150	0	150	MHz
t _W Pulse duration	LEAB or LEBA high	2.5	N	2.5		ns	
	Pulse duration	CLKAB or CLKBA high or low	3	7/2	3		115
t _{su} S		A before CLKAB↓ or B before CLKBA↓	3	7	3		
	Setup time	A before LEAB↓ or B before LEBA↓	2.5	7	2.5		ns
		CLKEN before CLK↓	2.5		2.5		
t _h Ho		A after CLKAB↓ or B after CLKBA↓	00		0		
	Hold time	A after LEAB↓ or B after LEBA↓	2 2		2		ns
		CLKEN after CLK↓	1		1		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM TO (INPUT) (OUTPUT)		V _{CC} = 5 V, T _A = 25°C		SN54ABT16600		SN74ABT16600		UNIT	
	(IIVI O1)	(0011-01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			150			150		150		MHz
t _{PLH}	A or B	B or A	1.5	2.5	3.6	1.5	4.2	1.5	4	ns
t _{PHL}		BOIA	1.5	3.2	4.5	1.5	5.1	1.5	4.9	115
t _{PLH}	LEAB or LEBA	B or A	2	3.2	4.5	2	5.6	2	5	ns
t _{PHL}	LEAD OF LEDA	BOIA	2	3.4	4.5	2	5.4	2	5	115
t _{PLH}	OLIVAD as OLIVDA	B or A	2	3.5	4.7	2	5.4	2	5.3	ns
^t PHL	CLKAB or CLKBA	BULK	2	3.5	4.3	2	5.2	2	5	115
^t PZH	<u> </u>	B or A	1.5	3.4	4.6	21.5	5.3	1.5	5.1	20
t _{PZL}	OEAB or OEBA	BULA	2	3.8	4.7	2	5.6	2	5.4	ns
t _{PHZ}	OEAB or OEBA	B or A	2	4.5	5.4	2	6.6	2	6.2	20
t _{PLZ}		DULA	1.5	3.4	4.7	1.5	5.8	1.5	5.4	ns

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns,
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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